




A layer transfer technology revolution – February 1, 2024


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Description

Dr. Thomas Uhrmann, EV Group's Business Development Director, discusses the company's recently launched EVG850 NanoCleave layer release system, which enables ultra-thin-layer transfer from silicon substrates with nanometer precision, revolutionizing 3D integration for advanced packaging and transistor scaling. He also shares his thoughts on the wider 2.5/3D market, and future plans for EV Group, alongside details of a recent contract win.

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